



SANYO Semiconductors

## DATA SHEET

An ON Semiconductor Company

# LV5694P — Monolithic Linear IC For Car Audio Systems Multi-Power Supply System IC

## Overview

LV5694P is a power supply IC suitable for USB/CD receiver system for car audio system. This IC enables drastic reduction of power dissipation compared to the existing model. This IC integrates 5 systems of regulator output, 2 systems of high side power switch, overcurrent protector, overvoltage protector and overheat protector (the package is HZIP15J).

## Features

- Low consumption current: 50μA (typ, only V<sub>DD</sub> output is in operation)
- 5 systems of regulator output
  - V<sub>DD</sub> for microcontroller: output voltage: 5.0V/3.3V (always ON), maximum output current: 300mA
  - For SWD5V: output voltage: 5V, maximum output current: 500mA
  - For CD: output voltage: 7.6V/8.1V, maximum output current: 2000mA
  - For illumination: output voltage: 9.0V, maximum output current: 500mA
  - For audio: output voltage: 8.45V, maximum output current: 800mA
- 2 lines of high side switch with interlock V<sub>CC</sub>
  - AMP: Maximum output current: 500mA, voltage difference between input and output: 0.5V
  - ANT: Maximum output current: 350mA, voltage difference between input and output: 0.5V
- Overcurrent protector
- Overvoltage protector: Typ 36V (All outputs are turned off)
- Overheat protector: Typ 175°C
- PchLDMOS is used in power output block

(Warning) The protector functions only improve the IC's tolerance and they do not guarantee the safety of the IC if used under the conditions out of safety range or ratings. Use of the IC such as use under over current protection range or thermal shutdown state may degrade the IC's reliability and eventually damage the IC.

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## Specifications

### Absolute Maximum Ratings at Ta = 25°C

Parameter	Conditions	Conditions	Ratings	Unit
Power supply voltage	V <sub>CC</sub> max		36	V
Power dissipation	Pd max	IC unit	1.5	W
		At using Al heat sink	5.6	W
		At infinity heat sink	32.5	W
Peak voltage	V <sub>CC</sub> peak	Regarding Bias wave, refer to below the pulse.	50	V
Junction temperature	Tj max		150	°C
Operating temperature	Topr		-40 to +85	°C
Storage temperature	Tstg		-55 to +150	°C

### Recommended Operating range at Ta = 25°C

Parameter	Conditions	Ratings	Unit
Power supply voltage rating 1	V <sub>DD</sub> output, SWD output	7 to 16	V
Power supply voltage rating 2	ILM output	10.8 to 16	V
Power supply voltage rating 3	Audio output, CD output	10 to 16	V
Power supply voltage rating 4	ANT output, AMP output	7.5 to 16	V

\* V<sub>CC1</sub> should be as follows: V<sub>CC1</sub> > V<sub>CC</sub> - 0.7V

### Electrical Characteristics at Ta = 25°C, V<sub>CC</sub> = V<sub>CC1</sub> = 14.4V (\*2)

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
V <sub>CC1</sub> input voltage	V <sub>CC1</sub>		V <sub>CC</sub> - 0.7V		16	V
Current drain	I <sub>CC</sub>	V <sub>DD</sub> no load, CTRL1/2/3 = [L/L/L]		50	100	μA
<b>CTRL1/2/3 Input</b>						
Low input voltage	V <sub>IL1</sub>		-	-	0.3	V
Middle1 input voltage	V <sub>IM1</sub>		0.9	1.18	1.45	V
Middle2 input voltage	V <sub>IM2</sub>		1.85	2.10	2.4	V
High input voltage	V <sub>IH1</sub>		2.95	3.29	5.5	V
Input impedance	R <sub>IH1</sub>	Input voltage ≤ 3.3V	280	400	520	kΩ
<b>IKCD/IKV<sub>DD</sub> Input</b>						
Low input voltage	V <sub>IL2</sub>		-	-	0.7	V
High input voltage	V <sub>IH2</sub>	IKCD IKV <sub>DD</sub>	V <sub>CC</sub> - 0.7V V <sub>CC1</sub> - 0.7V	-	-	V
<b>V<sub>DD</sub> output (5V/3.3V)</b>						
Output voltage	V <sub>O11</sub>	I <sub>O1</sub> = 200mA, IKV <sub>DD</sub> = V <sub>CC1</sub>	4.75	5.0	5.25	V
	V <sub>O12</sub>	I <sub>O1</sub> = 200mA, IKV <sub>DD</sub> = GND	3.16	3.3	3.45	V
Output current	I <sub>O1</sub>	V <sub>O11</sub> ≥ 4.70V, V <sub>O12</sub> ≥ 3.10V	300			mA
Line regulation	ΔV <sub>OLN1</sub>	7.5V < V <sub>CC1</sub> < 16V, I <sub>O1</sub> = 200mA		30	70	mV
Load regulation	ΔV <sub>OLD1</sub>	1mA < I <sub>O1</sub> < 200mA		70	150	mV
Dropout voltage 1	V <sub>DROP1</sub>	I <sub>O1</sub> = 200mA (V <sub>DD</sub> output 5V)		0.8	1.6	V
Dropout voltage 2	V <sub>DROP1'</sub>	I <sub>O1</sub> = 100mA (V <sub>DD</sub> output 5V)		0.4	0.8	V
Ripple rejection	R <sub>REJ1</sub>	f = 120Hz, I <sub>O1</sub> = 200mA	30	40		dB
Short circuit current	I <sub>S1</sub>	V <sub>O11</sub> , V <sub>O12</sub> = 0	50	150	340	mA
<b>AUDIO (8.45V) Output ; CTRL2 = [M1 or H]</b>						
Output voltage	V <sub>O3</sub>	I <sub>O3</sub> = 650mA	8.16	8.45	8.7	V
Output current	I <sub>O3</sub>	V <sub>O3</sub> ≥ 8.0V	800			mA
Line regulation	ΔV <sub>OLN3</sub>	10V < V <sub>CC</sub> < 16V, I <sub>O3</sub> = 650mA		30	90	mV
Load regulation	ΔV <sub>OLD3</sub>	1mA < I <sub>O3</sub> < 650mA		100	200	mV
Dropout voltage 1	V <sub>DROP3</sub>	I <sub>O3</sub> = 650mA		0.7	1.2	V
Dropout voltage 2	V <sub>DROP3'</sub>	I <sub>O3</sub> = 200mA		0.2	0.35	V
Ripple rejection	R <sub>REJ3</sub>	f = 120Hz, I <sub>O3</sub> = 650mA	40	50		dB
Short circuit current	I <sub>S3</sub>	V <sub>O3</sub> = 0	120	250	550	mA

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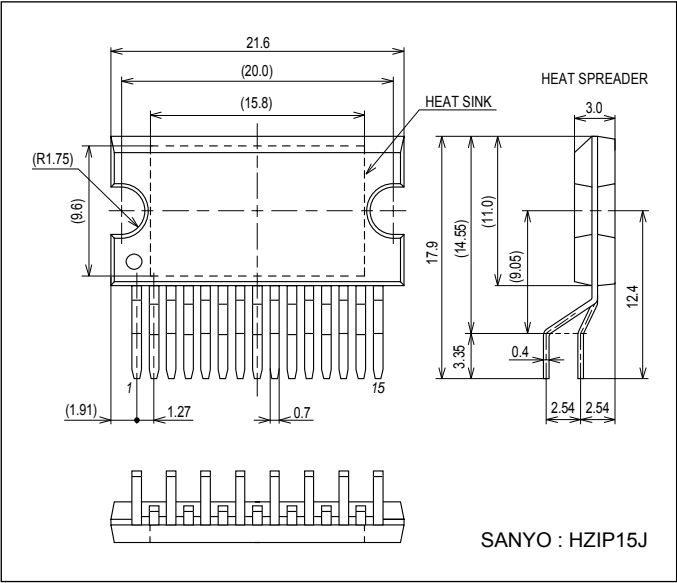
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Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
ILM (9V) Output ; CTRL1 =「M1 or H」						
Output voltage	V <sub>O4</sub>	I <sub>O4</sub> = 350mA	8.7	9.0	9.3	V
Output current	I <sub>O4</sub>	V <sub>O4</sub> ≥ 8.6V	500			mA
Line regulation	ΔV <sub>OLN4</sub>	10.8V < V <sub>CC</sub> < 16V, I <sub>O4</sub> = 350mA		40	100	mV
Load regulation	ΔV <sub>OLD4</sub>	1mA < I <sub>O4</sub> < 350mA		70	150	mV
Dropout voltage 1	V <sub>DROP4</sub>	I <sub>O4</sub> = 350mA		1.0	1.5	V
Dropout voltage 2	V <sub>DROP4'</sub>	I <sub>O4</sub> = 200mA		0.3	0.6	V
Ripple rejection	R <sub>REJ4</sub>	f = 120Hz, I <sub>O4</sub> = 350mA	40	50		dB
Short circuit current	I <sub>S4</sub>	V <sub>O4</sub> = 0	100	200	400	mA
AMP_HS-SW; CTRL3 =「M2 or H」						
Output voltage	V <sub>O5</sub>	I <sub>O5</sub> = 500mA		V <sub>CC</sub> -0.5	V <sub>CC</sub> -1.0	V
Output current	I <sub>O5</sub>	V <sub>O5</sub> ≥ V <sub>CC</sub> -1.0V	500			mA
Short circuit current	I <sub>S5</sub>	V <sub>O5</sub> = 0	120	250	500	mA
ANT_HS-SW; CTRL3 =「M1 or H」						
Output voltage	V <sub>O6</sub>	I <sub>O6</sub> = 500mA		V <sub>CC</sub> -0.5	V <sub>CC</sub> -1.0	V
Output current	I <sub>O6</sub>	V <sub>O6</sub> ≥ V <sub>CC</sub> -1.0V	350			mA
Short circuit current	I <sub>S6</sub>	V <sub>O6</sub> = 0	100	200	450	mA
SWD5V; CTRL2 =「M2 or H」						
Output voltage	V <sub>O7</sub>	I <sub>O7</sub> = 350mA	4.75	5.0	5.25	V
Output current	I <sub>O7</sub>	V <sub>O7</sub> ≥ 4.7V	500			mA
Line regulation	ΔV <sub>OLN7</sub>	10V < V <sub>CC</sub> < 16V, I <sub>O7</sub> = 350mA		30	70	mV
Load regulation	ΔV <sub>OLD7</sub>	1mA < I <sub>O7</sub> < 350mA		70	150	mV
Dropout voltage	V <sub>DROP7</sub>	I <sub>O7</sub> = 350mA		0.8	1.6	V
Ripple rejection	R <sub>REJ7</sub>	f = 120Hz, I <sub>O7</sub> = 350mA	40	50		dB
Short circuit current	I <sub>S7</sub>	V <sub>O7</sub> = 0	100	200	450	mA
CD(7.6/8.1V output); CTRL1 =「M2 or H」						
Output voltage	V <sub>O81</sub>	I <sub>O8</sub> = 1300mA, I <sub>KCD</sub> =GND	7.2	7.6	8.0	V
	V <sub>O82</sub>	I <sub>O8</sub> = 1300mA, I <sub>KCD</sub> =V <sub>CC</sub>	7.7	8.1	8.5	V
Output current	I <sub>O8</sub>	V <sub>O81</sub> ≥ 7.1V, V <sub>O82</sub> ≥ 7.5V	2000			mA
Line regulation	ΔV <sub>OLN8</sub>	10.5V < V <sub>CC</sub> < 16V, I <sub>O8</sub> = 1300mA		40	100	mV
Load regulation	ΔV <sub>OLD8</sub>	10mA < I <sub>O8</sub> < 1300mA		70	200	mV
Dropout voltage 1	V <sub>DROP8</sub>	I <sub>O8</sub> = 1300mA		1.3	1.5	V
Dropout voltage 2	V <sub>DROP8'</sub>	I <sub>O8</sub> = 350mA		0.35	0.7	V
Ripple rejection	R <sub>REJ8</sub>	f = 120Hz, I <sub>O8</sub> = 1300mA	40	50		dB
Short circuit current	I <sub>S8</sub>	V <sub>O81</sub> = 0, V <sub>O82</sub> = 0	300	550	1000	mA
Over voltage detection						
Over voltage detection voltage	V <sub>OVP</sub>	V <sub>CC</sub> , All output stop	34	36	38	V

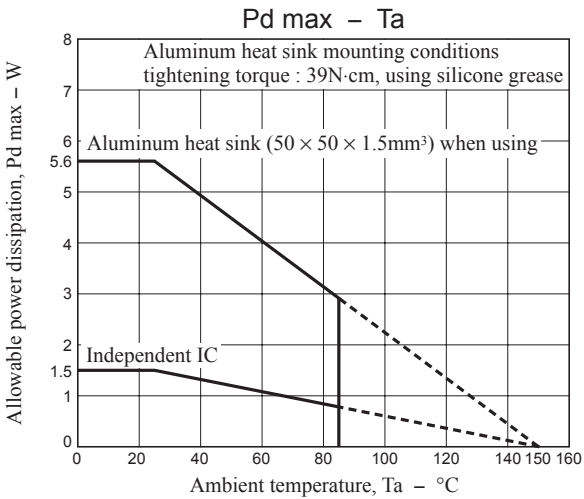
\*2: The entire specification has been defined based on the tests performed under the conditions where T<sub>j</sub> and T<sub>a</sub> (=25°C) are almost equal. There tests were performed with pulse load to minimize the increase of junction temperature (T<sub>j</sub>).

Package Dimensions

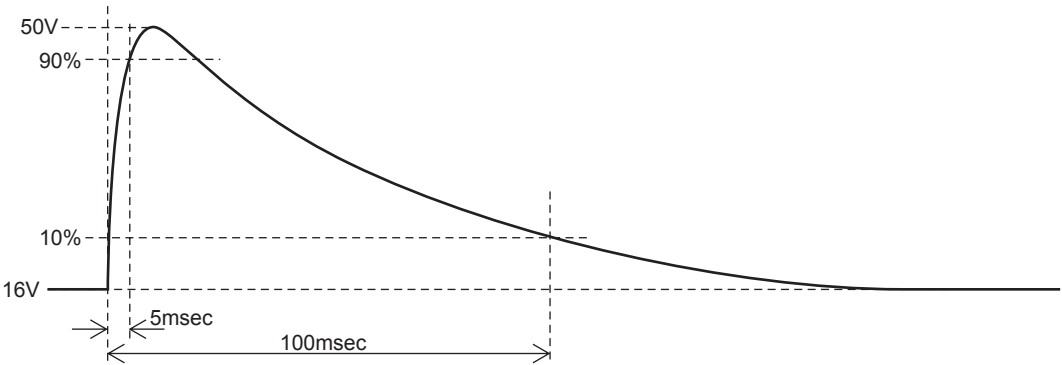
unit : mm (typ)  
3395



• Allowable power dissipation derating curve



• Waveform applied during surge test



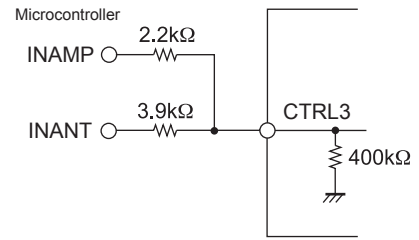
## LV5694P

**CTRL Pin Output Truth Table** (each output is controllable by 4-value input)

INAMP	INANT	CTRL3	AMP	ANT
L	L	L	OFF	OFF
L	H	M1	OFF	ON
H	L	M2	ON	OFF
H	H	H	ON	ON

CTRL2	SWD5V	AUDIO
L	OFF	OFF
M1	OFF	ON
M2	ON	OFF
H	ON	ON

CTRL1	CD	ILM
L	OFF	OFF
M1	OFF	ON
M2	ON	OFF
H	ON	ON



### (Warning) Usage of CTRL pin

When CTRL pin transits between L and M2, since it passes M1, ILM/AUDIO/ANT is turned on for a moment. Likewise, when CTRL pin transits between H and M1, since it passes M2, ILM/AUDIO/ANT is turned off for a moment. To avoid operation failure by the above factors, please refer to (1) and (2) as shown below for precaution.

- Do not connect parasitic capacitor to CTRL as much as possible.
- If use of capacitor for CTRL is required, keep the resistance value as low as possible.  
(Recommendation level: 2.2kΩ / 3.9kΩ)
- Make sure that the output load capacitor has enough margin against the voltage fluctuation due to instantaneous ON/OFF.

(1) The time until a reaction occurs in output after shifting from CTRL ON to OFF (typ)

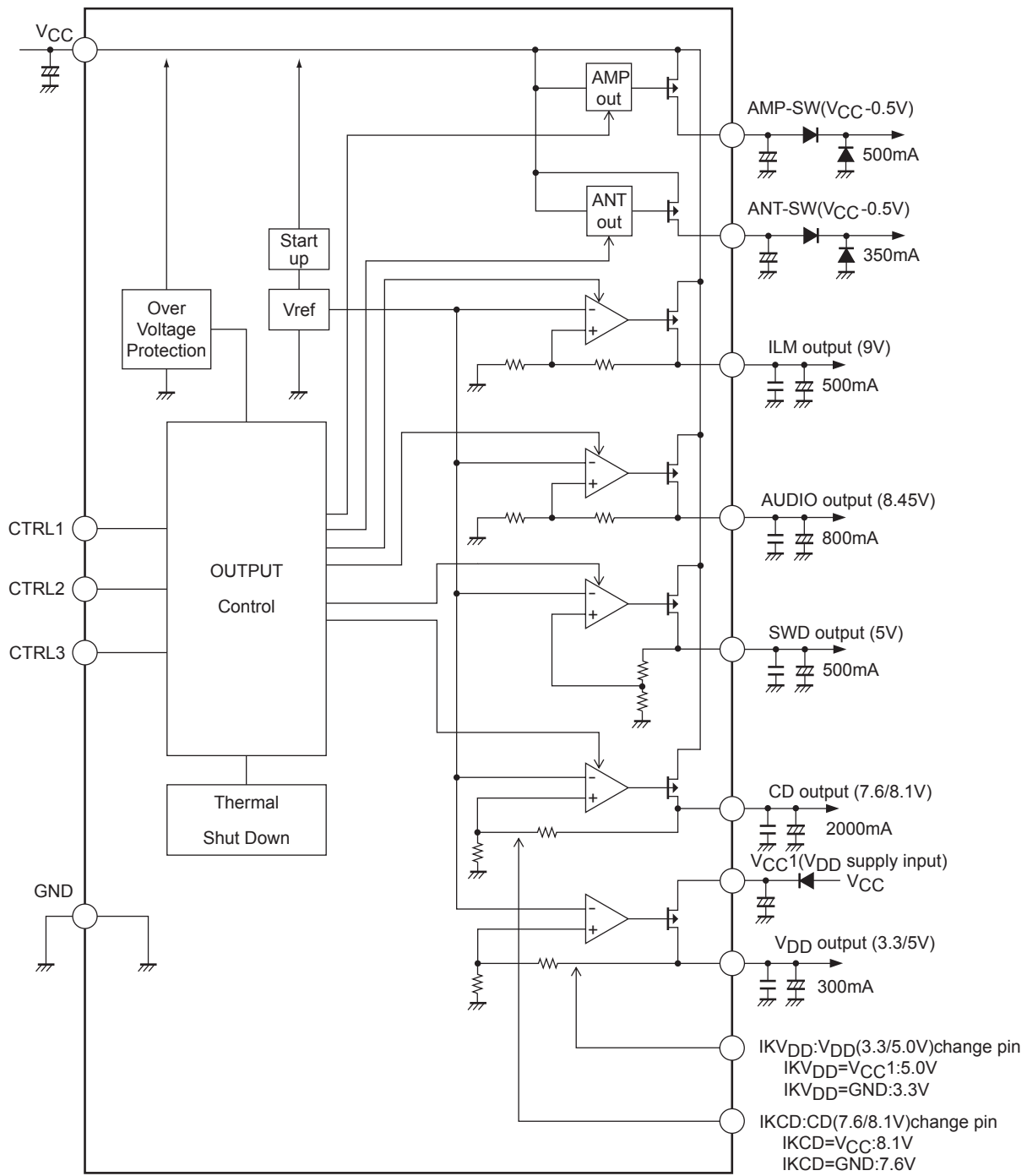
OFF → ON time	27°C
CTRL1 → ILM	0.95μs
CTRL2 → AUDIO	1.33μs
CTRL3 → ANT	2.86μs

Due to quality fluctuation of the ICs in manufacturing process, the above-mentioned time can be shortened by 10 to 20%.

(2) The time until output starts to react after shifting from CTRL ON→OFF control (typ):

All output: 200ns to 300ns

● Block Diagram



# Pin Function

Pin No.	Pin name	Description	Equivalent Circuit
1	ILM	ILM output pin ON when CTRL1 = M1, H 9V/0.5A	
2	GND	GND pin	
3	CD	CD output pin ON when CTRL1 = M2, H 8.1V/2A (IKCD=VCC) 7.6V/2A (IKCD=GND)	
4 6 8	CTRL1 CTRL2 CTRL3	CTRL1/2/3 input pin Four value input	
5	AUDIO	AUDIO output pin ON when CTRL2 = M1, H 8.45V/0.8A	
7	SWD	SWD output pin ON when CTRL2 = M2, H 5V/0.5A	

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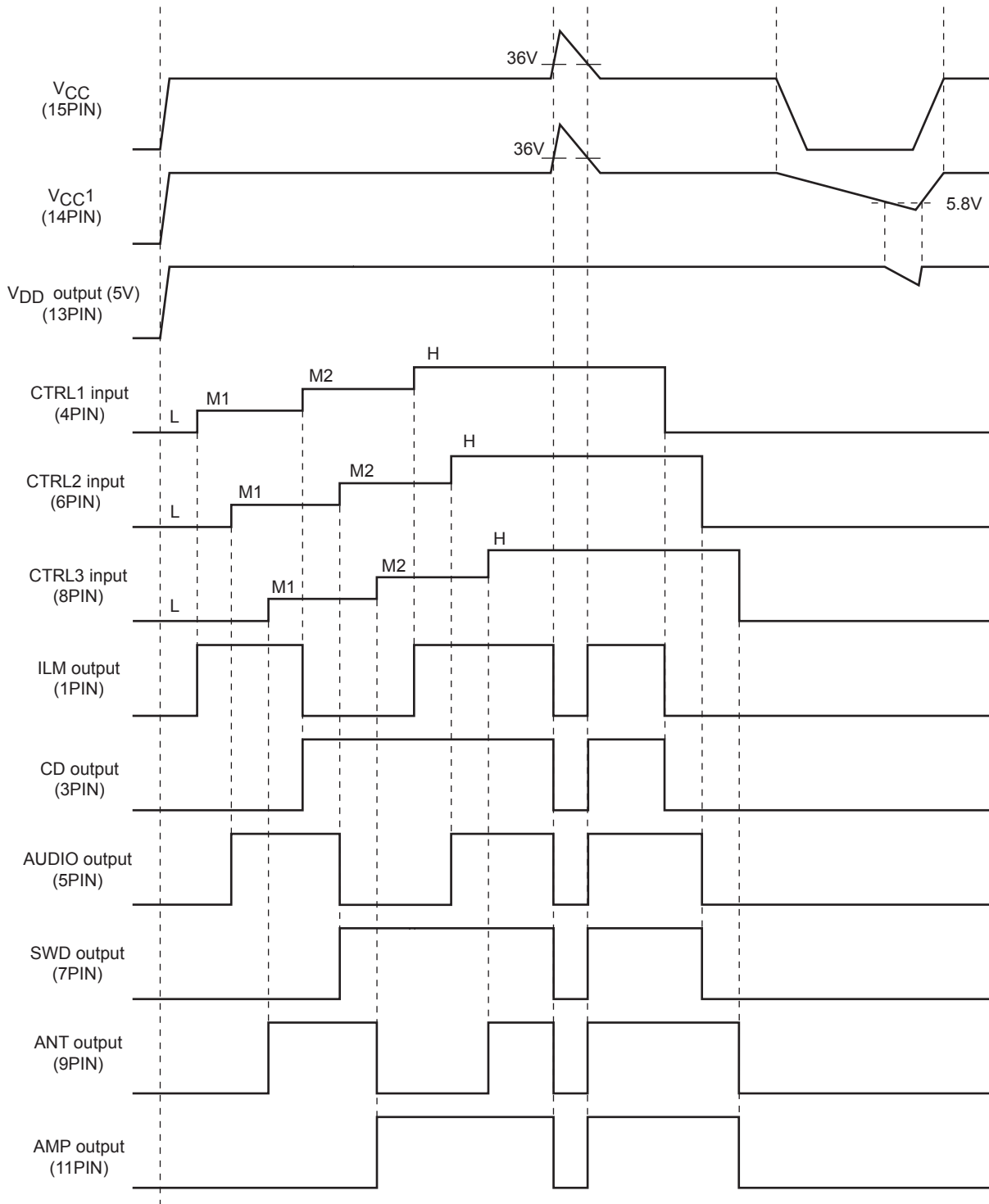
# LV5694P

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Pin No.	Pin name	Description	Equivalent Circuit
9	ANT	ANT output pin ON when CTRL3 = M1, H $V_{CC}$ -0.5V/350mA	
10	IKCD	CD voltage control input pin	
11	AMP	AMP output pin ON when CTRL2 = M2, H $V_{CC}$ -0.5V/500mA	
12	IKVDD	VDD voltage control input pin $V_{CC1}$ /GND	
13	VDD	VDD output pin 5.0V/0.3A (IKVDD = $V_{CC1}$ ) 3.3V/0.3A (IKVDD = GND)	
14	$V_{CC1}$	$V_{DD}$ power supply pin	
15	$V_{CC}$	Power supply pin	

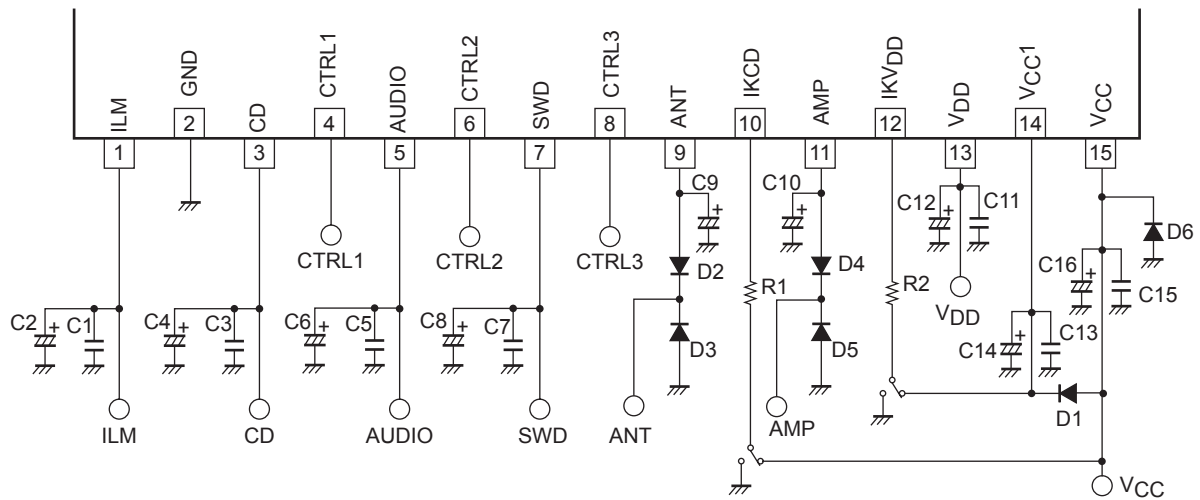


Timing Chart



\*The above values are obtained when typ.

## Applied circuit example



## Peripheral parts list

Name of part	Description	Recommended value	Remarks
C2, C4, C6, C8, C12	Output stabilization capacitor	10 $\mu$ F or more*	Electrolytic capacitor
C1, C3, C5, C7, C11	Output stabilization capacitor	0.22 $\mu$ F or more*	Ceramic capacitor
C14, C16	Power supply bypass capacitor	100 $\mu$ F or more	These capacitors must be placed near the V <sub>CC</sub> and GND pins.
C13, C15	Oscillation prevention capacitor	0.22 $\mu$ F or more	
C9, C10	AMP/ANT output stabilization capacitor	2.2 $\mu$ F or more	
R1, R2	Resistance for protection	10 to 100k $\Omega$	
D1	Diode for prevention of backflow		Meeting the specifications of the rush electric current in a true use state
D2, D3, D4, D5	Diode for internal element protection	SANYO SB1003M3	
D6	Diode for internal element protection	SANYO SB1003M3	When a minus number surge is applied

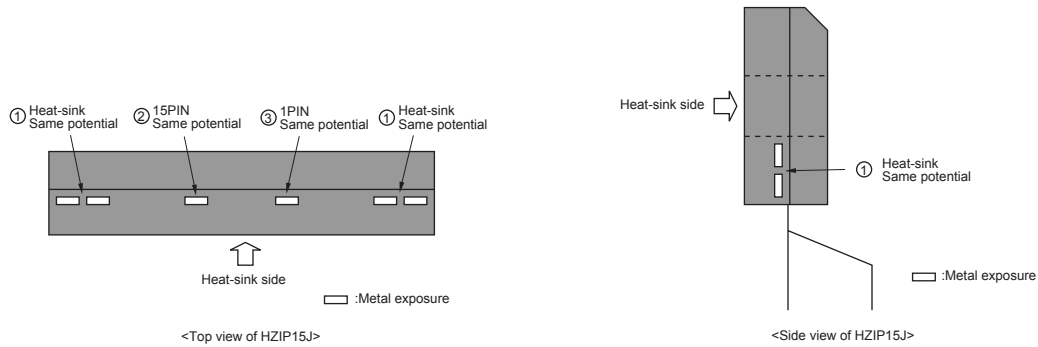
\*: Make sure that the capacitors of the output pins are 10 $\mu$ F or higher and meets the condition of ESR is 0.001 to 10 $\Omega$  (ceramic capacitor alone can be used.), in which voltage/ temperature fluctuation and unit differences are taken into consideration. Moreover, RF characteristics of electrolytic capacitor should be sufficient.

## LV5694P

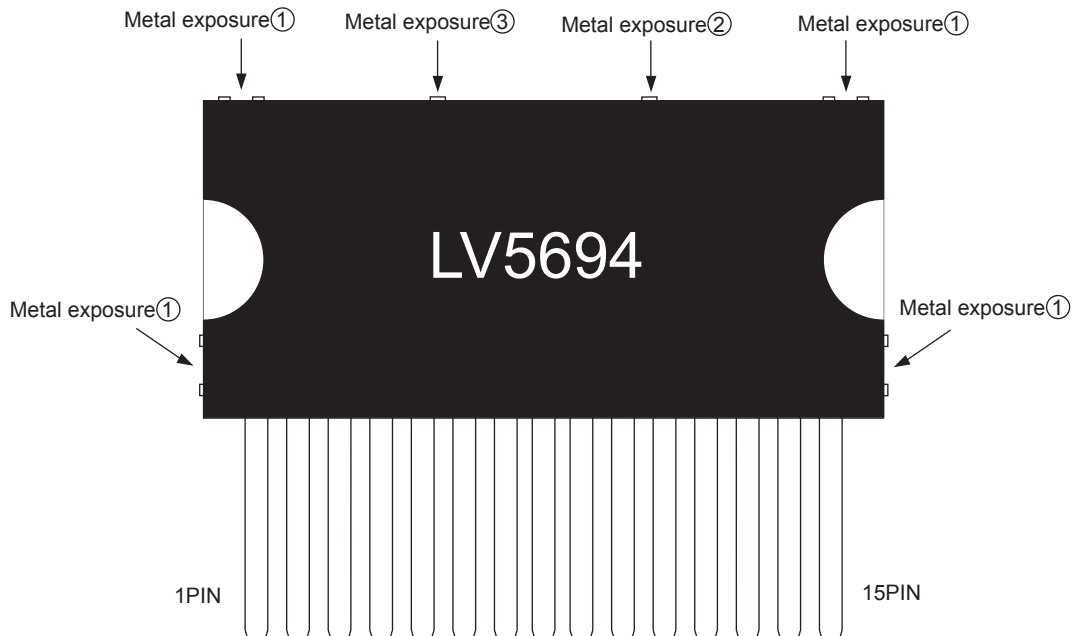
### Caution for implementing LV5694P to a system board

The package of LV5694P is HZIP15J which has some metal exposures other than connection pins and heatsink as shown in the diagram below. The electrical potentials of (2) and (3) are the same as those of pin 15 and pin 1, respectively. (2) (=pin 15) is the  $V_{CC}$  pin and (3) (=pin 1) is the ILM (regulator) output pin. When you implement the IC to the set board, make sure that the bolts and the heatsink are out of touch from (2) and (3). If the metal exposures touch the bolts which has the same electrical potential with GND, GND short occurs in ILM output and  $V_{CC}$ . The exposures of (1) are connected to heatsink which has the same electrical potential with substrate of the IC chip (GND). Therefore, (1) and GND electrical potential of the set board can connect each other.

- HZIP15J outline



- Frame diagram (LV5694P) \*In the system power supply other than LV5694P, pin assignment may differ.



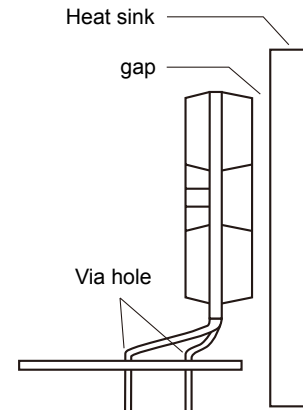
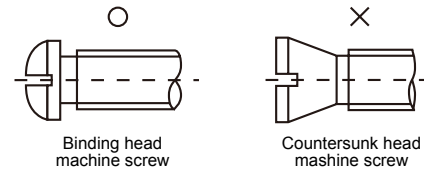
## HZIP15J Heat sink attachment

Heat sinks are used to lower the semiconductor device junction temperature by leading the heat generated by the device to the outer environment and dissipating that heat.

- a. Unless otherwise specified, for power ICs with tabs and power ICs with attached heat sinks, solder must not be applied to the heat sink or tabs.

- b. Heat sink attachment

- Use flat-head screws to attach heat sinks.
- Use also washer to protect the package.
- Use tightening torques in the ranges 39-59Ncm(4-6kgcm) .
- If tapping screws are used, do not use screws with a diameter larger than the holes in the semiconductor device itself.
- Do not make gap, dust, or other contaminants to get between the semiconductor device and the tab or heat sink.
- Take care a position of via hole .
- Do not allow dirt, dust, or other contaminants to get between the semiconductor device and the tab or heat sink.
- Verify that there are no press burrs or screw-hole burrs on the heat sink.
- Warping in heat sinks and printed circuit boards must be no more than 0.05 mm between screw holes, for either concave or convex warping.
- Twisting must be limited to under 0.05 mm.
- Heat sink and semiconductor device are mounted in parallel.
- Take care of electric or compressed air drivers
- The speed of these torque wrenches should never exceed 700 rpm, and should typically be about 400 rpm.



- c. Silicone grease

- Spread the silicone grease evenly when mounting heat sinks.
- Sanyo recommends YG-6260 (Momentive Performance Materials Japan LLC)

- d. Mount

- First mount the heat sink on the semiconductor device, and then mount that assembly on the printed circuit board.
- When attaching a heat sink after mounting a semiconductor device into the printed circuit board, when tightening up a heat sink with the screw, the mechanical stress which is impossible to the semiconductor device and the pin doesn't hang.

- e. When mounting the semiconductor device to the heat sink using jigs, etc.,

- Take care not to allow the device to ride onto the jig or positioning dowel.
- Design the jig so that no unreasonable mechanical stress is not applied to the semiconductor device.

- f. Heat sink screw holes

- Be sure that chamfering and shear drop of heat sinks must not be larger than the diameter of screw head used.
- When using nuts, do not make the heat sink hole diameters larger than the diameter of the head of the screws used. A hole diameter about 15% larger than the diameter of the screw is desirable.
- When tap screws are used, be sure that the diameter of the holes in the heat sink are not too small. A diameter about 15% smaller than the diameter of the screw is desirable.

- g. There is a method to mount the semiconductor device to the heat sink by using a spring band. But this method is not recommended because of possible displacement due to fluctuation of the spring force with time or vibration.

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